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Plastic Medium-Power Complementary Silicon Transistors

These devices are designed for general-purpose amplifier and low-speed switching applications.

Features

- High DC Current Gain
 - $h_{FE} = 2500 \text{ (Typ)} @ I_C = 4.0 \text{ Adc}$
- Collector Emitter Sustaining Voltage @ 100 mAdc
 V_{CEO(sus)} = 80 Vdc (Min) BDX53B, 54B = 100 Vdc (Min) – BDX53C, 54C
- Low Collector–Emitter Saturation Voltage
 - $V_{CE(sat)} = 2.0 \text{ Vdc (Max)} @ I_C = 3.0 \text{ Adc}$ $= 4.0 \text{ Vdc (Max)} @ I_C = 5.0 \text{ Adc}$
- Monolithic Construction with Built-In Base-Emitter Shunt Resistors
- These Devices are Pb-Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage BDX53B, BDX54B BDX53C, BDX54C	V _{CEO}	80 100	Vdc
Collector–Base Voltage BDX53B, BDX54B BDX53C, BDX54C	V _{CB}	80 100	Vdc
Emitter–Base Voltage	V _{EB}	5.0	Vdc
Collector Current – Continuous – Peak	Ι _C	8.0 12	Adc
Base Current	Ι _Β	0.2	Adc
Total Device Dissipation @ $T_C = 25^{\circ}C$ Derate above $25^{\circ}C$	PD	65 0.48	W ₩/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	70	°C/W
Thermal Resistance, Junction-to-Case	R_{\thetaJC}	1.92	°C/W

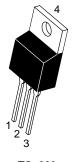
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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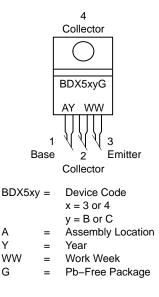
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DARLINGTON 8 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 80–100 VOLTS, 65 WATTS



TO-220 CASE 221A STYLE 1

MARKING DIAGRAM & PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

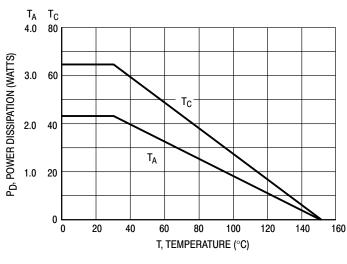


Figure 1. Power Derating

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS			•	•	
Collector–Emitter Sustaining Voltage (Note 1) ($I_C = 100$ mAdc, $I_B = 0$)	BDX53B, BDX54B BDX53C, BDX54C	V _{CEO(sus)}	80 100		Vdc
Collector Cutoff Current $(V_{CE} = 40 \text{ Vdc}, I_B = 0)$ $(V_{CE} = 50 \text{ Vdc}, I_B = 0)$	BDX53B, BDX54B BDX53C, BDX54C	I _{CEO}		0.5 0.5	mAdc
Collector Cutoff Current $(V_{CB} = 80 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 100 \text{ Vdc}, I_E = 0)$	BDX53B, BDX54B BDX53C, BDX54C	I _{CBO}		0.2 0.2	mAdc
ON CHARACTERISTICS (Note 1)					
DC Current Gain (I _C = 3.0 Adc, V _{CE} = 3.0 Vdc)		h _{FE}	750	-	-
Collector–Emitter Saturation Voltage $(I_C = 3.0 \text{ Adc}, I_B = 12 \text{ mAdc})$		V _{CE(sat)}		2.0 4.0	Vdc
Base–Emitter Saturation Voltage ($I_C = 3.0 \text{ Adc}, I_C = 12 \text{ mA}$)		V _{BE(sat)}	_	2.5	Vdc
DYNAMIC CHARACTERISTICS					
Small–Signal Current Gain		hea	4.0	_	_

Small–Signal Current Gain (I _C = 3.0 Adc, V _{CE} = 4.0 Vdc, f = 1.0 MHz)		h _{fe}	4.0	-	-
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 0.1 MHz)	BDX53B, 53C BDX54B, 54C	C _{ob}		300 200	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2%.

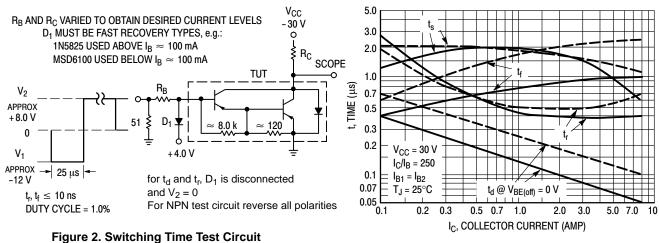


Figure 3. Switching Times

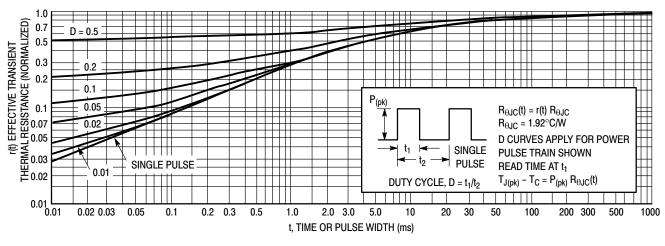


Figure 4. Thermal Response

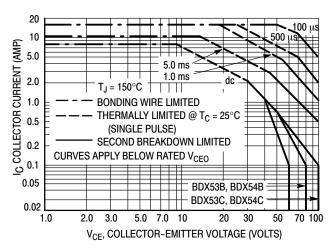


Figure 5. Active–Region Safe Operating Area

There are two limitations on the power handling ability of a transistor average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on $T_{J(pk)} = 150^{\circ}$ C; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} < 150^{\circ}$ C. $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

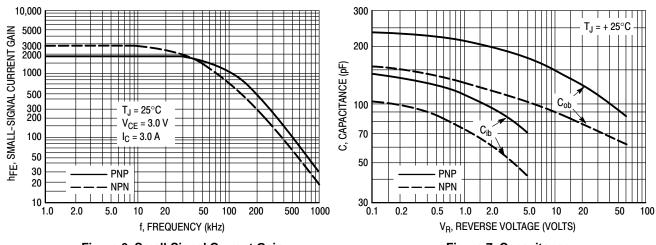


Figure 6. Small-Signal Current Gain

Figure 7. Capacitance

NPN BDX53B, 53C

PNP BDX54B, 54C

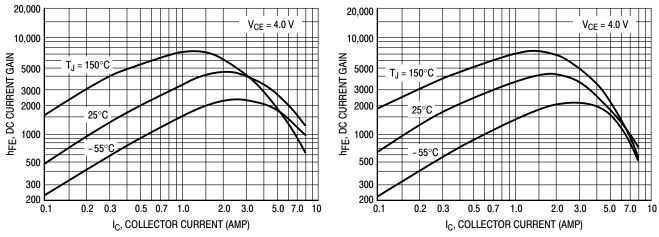
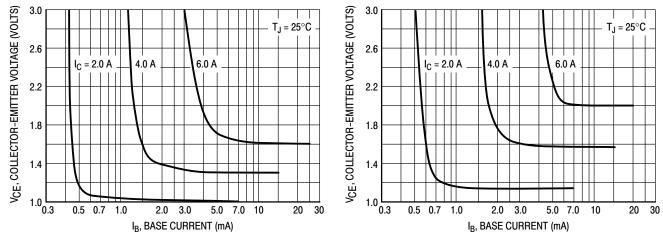
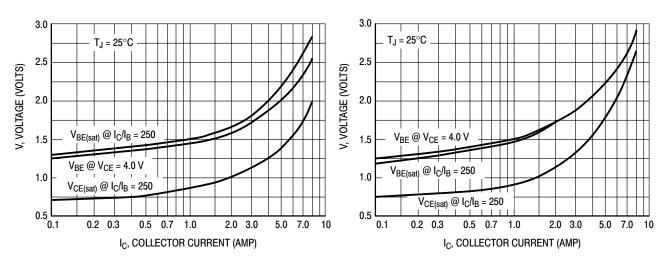
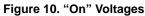


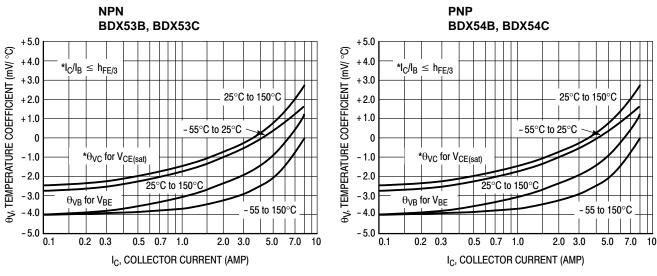
Figure 8. DC Current Gain

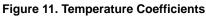


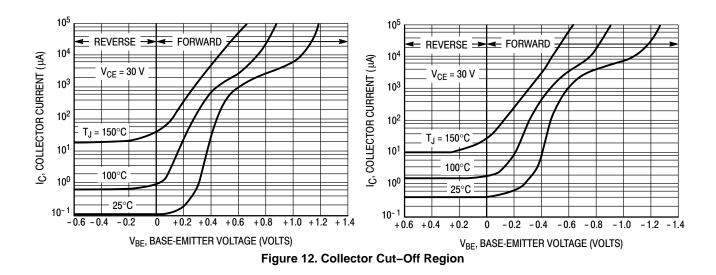


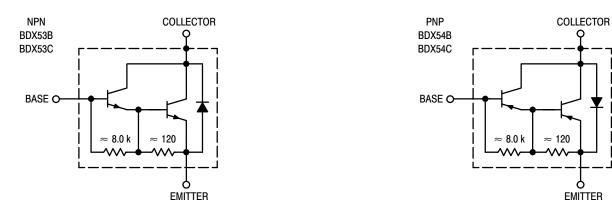














ORDERING INFORMATION

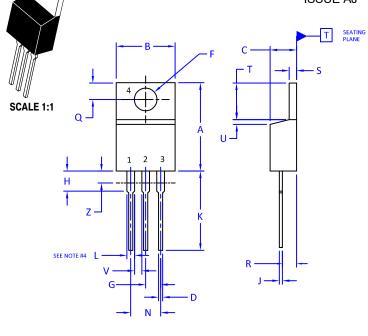
Device	Package	Shipping [†]
BDX53BG	TO-220 (Pb-Free)	50 Units / Rail
BDX53CG	TO-220 (Pb-Free)	50 Units / Rail
BDX54BG	TO-220 (Pb-Free)	50 Units / Rail
BDX54CG	TO-220 (Pb-Free)	50 Units / Rail

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DATE 05 NOV 2019



TO-220 CASE 221A-09 ISSUE AJ



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.

2. CONTROLLING DIMENSION: INCHES

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

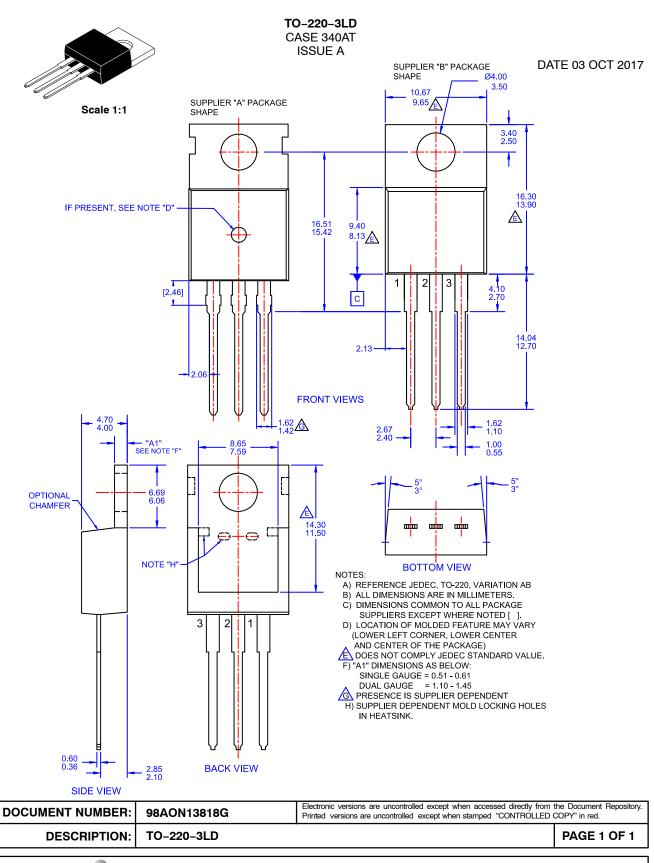
4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIME	ETERS
DIM	MIN.	MAX.	MIN.	MAX.
А	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1: PIN 1. 2. 3. 4.	EMITTER	STYLE 2: PIN 1. 2. 3. 4.	COLLECTOR	3.	CATHODE ANODE GATE ANODE	STYLE 4: PIN 1. 2. 3. 4.	MAIN TERMINAL 1 MAIN TERMINAL 2 GATE MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELAY
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10	:	STYLE 11:		STYLE 12	:
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

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